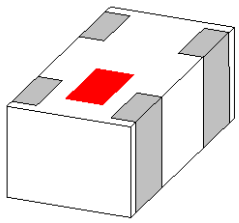
CP1005 Series (Preliminary)

Multilayer Chip Couplers

Features

❖ Monolithic SMD with ultra-small, low-profiled, and light-weight type.



Applications

❖0.4 ~ 6 GHz wireless communication systems, including DECT/PACS/PHS/GSM/DCS phones, WLAN card, Bluetooth modules, etc.

Specifications

Part Number	Frequency (MHz)	Insertion Loss (dB)	VSWR	Coupling (dB)	Isolation (dB)
CP1005-16C1747_	1710 ~ 1785	0.3 max.	1.3 max.	16.0 ± 1.0	29.0

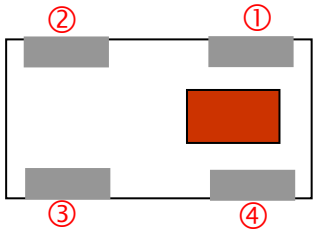
Q'ty/Reel (pcs) : 10000
Operating Temperature Range : -40 ~ +85 °C
Storage Temperature Range : +5 ~ +35 °C, Humidity 45~75%RH
Storage Period : 12 months max.
Power Capacity : 3W max.

Part Number

CP ① 1005 ② - 16 ③ C ④ 1747 ⑤ □ ⑥ /LF ⑦

① Type	CP : Coupler	② Dimensions (L × W)	1.0 × 0.5 mm
③ Coupling	16 : 16.0 dB	④ Specification Code	C
⑤ Central Frequency	1747 : 1747MHz	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	=lead-containing /LF=lead-free		

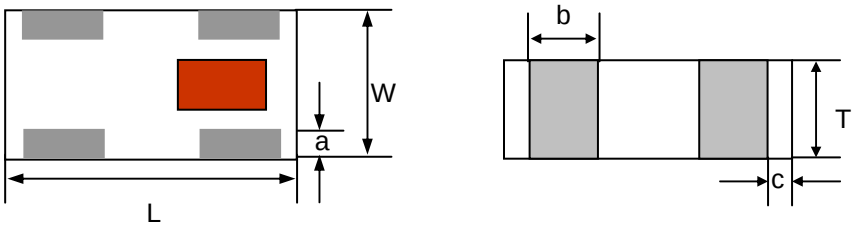
Terminal Configuration



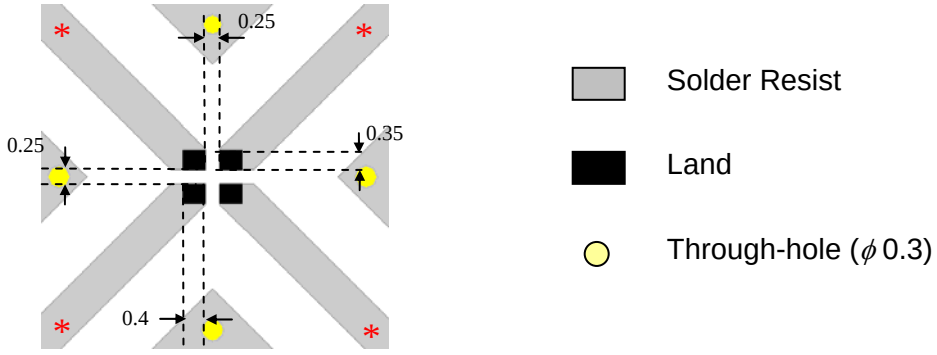
No.	Terminal Name	No.	Terminal Name
①	Out	③	Coupling
②	IN	④	Termination

Dimensions and Recommended PC Board Pattern

Unit : mm



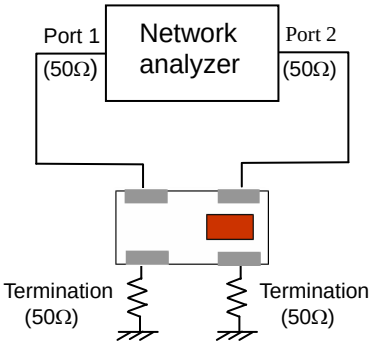
Mark	L	W	T	a	b	c
Dimensions	1.0 ± 0.1	0.5 ± 0.1	0.37 ± 0.05	0.1 +0.1/-0.05	0.25 +0.1/-0.05	0.1 +0.1/-0.05



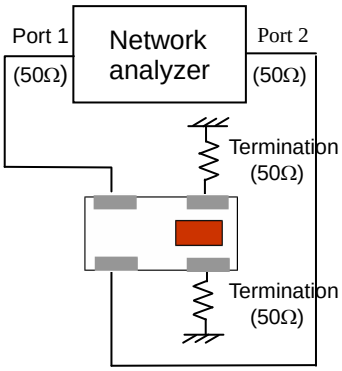
* Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.

Measuring Diagram

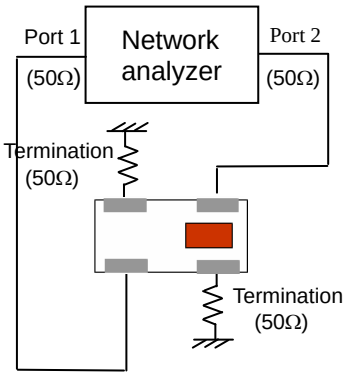
Attenuation



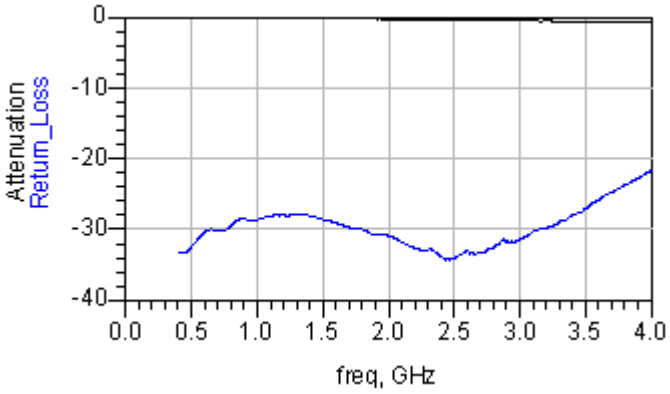
Coupling

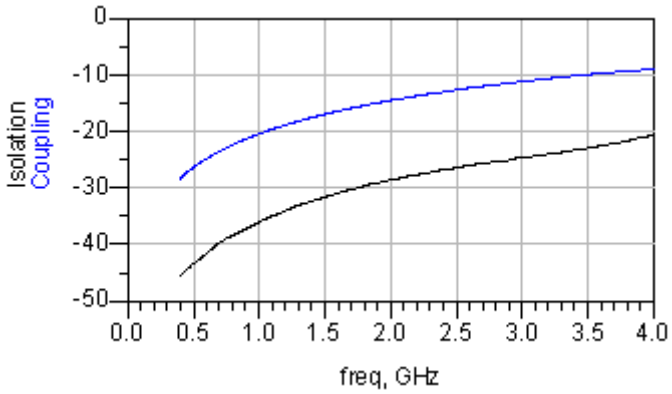


Isolation



Typical Electrical Characteristics (T=25°C)





Notes

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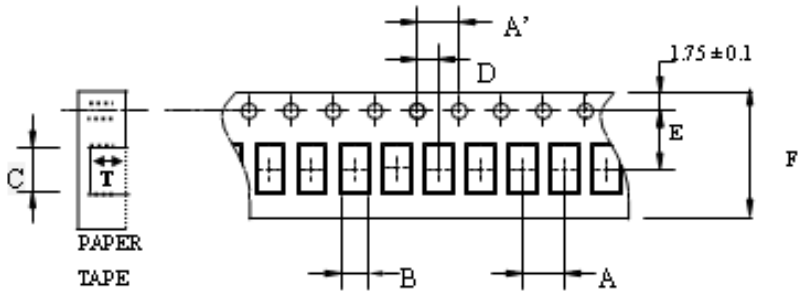
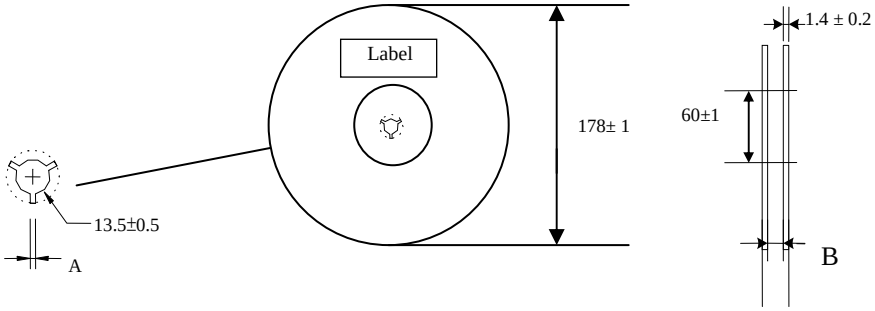
Taping Specifications

❖Tape Dimensions (Unit: mm) & Quantity



Type	A	A'	B	C	D	E	F	T	Quantity/reel	Tape material
1005	2.0± 0.05	4.0± 0.1	0.62± 0.03	1.12± 0.03	2.0± 0.05	3.5± 0.05	8.0± 0.1	0.45± 0.03	10,000pcs	Paper

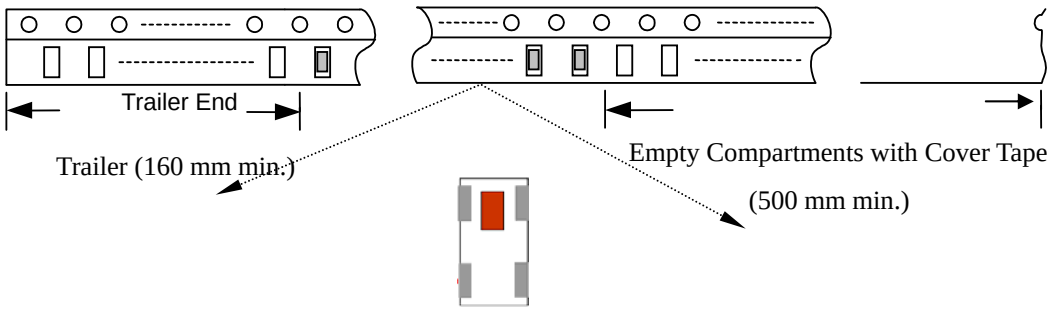
❖Reel Dimensions (Unit: mm)



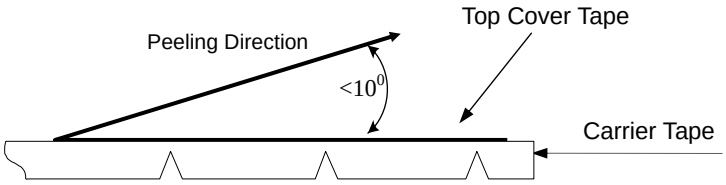
Label: Customer's Name,
ACX P/N, Q'ty, Date,
ACX Corp.

Type	A	B
1005	2.3±0.5	9.0±0.3

❖Leader and Trailer Tape



❖**Peel-off Force**



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300±10 mm/min .

❖**Storage Conditions**

(1) Temperature: 15 ~35℃, relative humidity (RH): 45~75%.
(2) Non-corrosive environment

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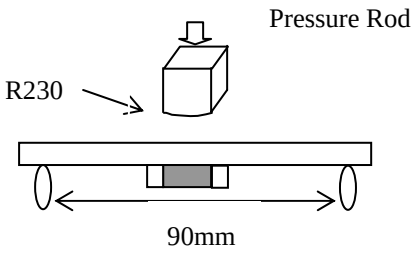
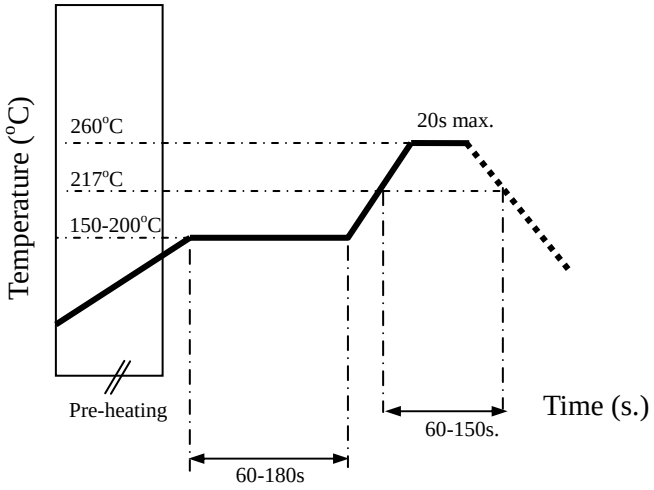
Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	1. No apparent damage 2. More than 95% of the terminal electrode shall be covered with new solder.	1. Preheat: 120± 5 °C 2. Solder: 245± 5°C for 5± 1 sec
Soldering strength (Termination Adhesion)	1. 3N minimum	1. Solder specimen onto test jig. 2. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction
Deflection (Substrate Bending)	1. No apparent damage 2. Fulfill the electrical specification	1. Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile. 2. Apply a bending force of 2mm deflection 
Heat/Humidity Resistance	1. No apparent damage 2. Fulfill the electrical specification after test	1. Temperature: 85± 2°C 2. Humidity: 90% ~ 95% RH 3. Duration: 1000±48hrs 4. Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	1. No apparent damage 2. Fulfill the electrical specification after test	1. One cycle/step 1：125 ± 5°C for 30 min step 2：- 40 ± 5°C for 30 min 2. No of cycles：100 3. Recovery:1-2 hrs
Low Temperature Resistance	1. No apparent damage 2. Fulfill the electrical specification after test	1. Temperature: -40± 5 °C 2. Duration: 500 ±24hrs 3. Recovery: 1-2hrs

Soldering Conditions

❖**Typical Soldering Profile for Lead-free Process**

Reflow Soldering :



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